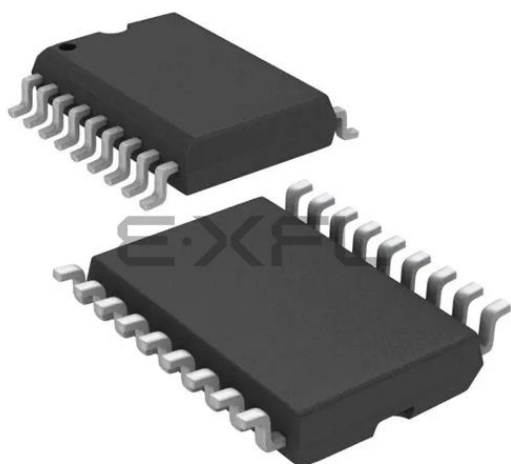




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c621a-20i-so

1.0 GENERAL DESCRIPTION

The PIC16C62X devices are 18 and 20-Pin ROM/EPROM-based members of the versatile PICmicro® family of low cost, high performance, CMOS, fully-static, 8-bit microcontrollers.

All PICmicro microcontrollers employ an advanced RISC architecture. The PIC16C62X devices have enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16C62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16C620A, PIC16C621A and PIC16CR620A have 96 bytes of RAM. The PIC16C622(A) has 128 bytes of RAM. Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16C62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16C62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (Power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and RESET.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock-up.

A UV-erasable Cerdip-packaged version is ideal for code development while the cost effective One-Time-Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16C62X mid-range microcontroller families.

A simplified block diagram of the PIC16C62X is shown in Figure 3-1.

The PIC16C62X series fits perfectly in applications ranging from battery chargers to low power remote sensors. The EPROM technology makes

customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low cost, low power, high performance, ease of use and I/O flexibility make the PIC16C62X very versatile.

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to PIC16C62X family of devices (Appendix B). The PIC16C62X family fills the niche for users wanting to migrate up from the PIC16C5X family and not needing various peripheral features of other members of the PIC16XX mid-range microcontroller family.

1.2 Development Support

The PIC16C62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low cost development programmer and a full-featured programmer. Third Party "C" compilers are also available.

PIC16C62X

NOTES:

TABLE 3-1: PIC16C62X PINOUT DESCRIPTION

Name	DIP/SOIC Pin #	SSOP Pin #	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	18	I	ST/CMOS	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
MCLR/VPP	4	4	I/P	ST	Master Clear (Reset) input/programming voltage input. This pin is an Active Low Reset to the device.
RA0/AN0	17	19	I/O	ST	PORTA is a bi-directional I/O port. Analog comparator input Analog comparator input Analog comparator input or VREF output Analog comparator input /output Can be selected to be the clock input to the Timer0 timer/counter or a comparator output. Output is open drain type.
RA1/AN1	18	20	I/O	ST	
RA2/AN2/VREF	1	1	I/O	ST	
RA3/AN3	2	2	I/O	ST	
RA4/T0CKI	3	3	I/O	ST	
RB0/INT	6	7	I/O	TTL/ST ⁽¹⁾	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. RB0/INT can also be selected as an external interrupt pin. Interrupt-on-change pin. Interrupt-on-change pin. Interrupt-on-change pin. Serial programming clock. Interrupt-on-change pin. Serial programming data.
RB1	7	8	I/O	TTL	
RB2	8	9	I/O	TTL	
RB3	9	10	I/O	TTL	
RB4	10	11	I/O	TTL	
RB5	11	12	I/O	TTL	
RB6	12	13	I/O	TTL/ST ⁽²⁾	
RB7	13	14	I/O	TTL/ST ⁽²⁾	
Vss	5	5,6	P	—	Ground reference for logic and I/O pins.
VDD	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: O = output I/O = input/output P = power
 — = Not used I = Input ST = Schmitt Trigger input
 TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
 2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

PIC16C62X

4.2 Data Memory Organization

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

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PIC16C62X

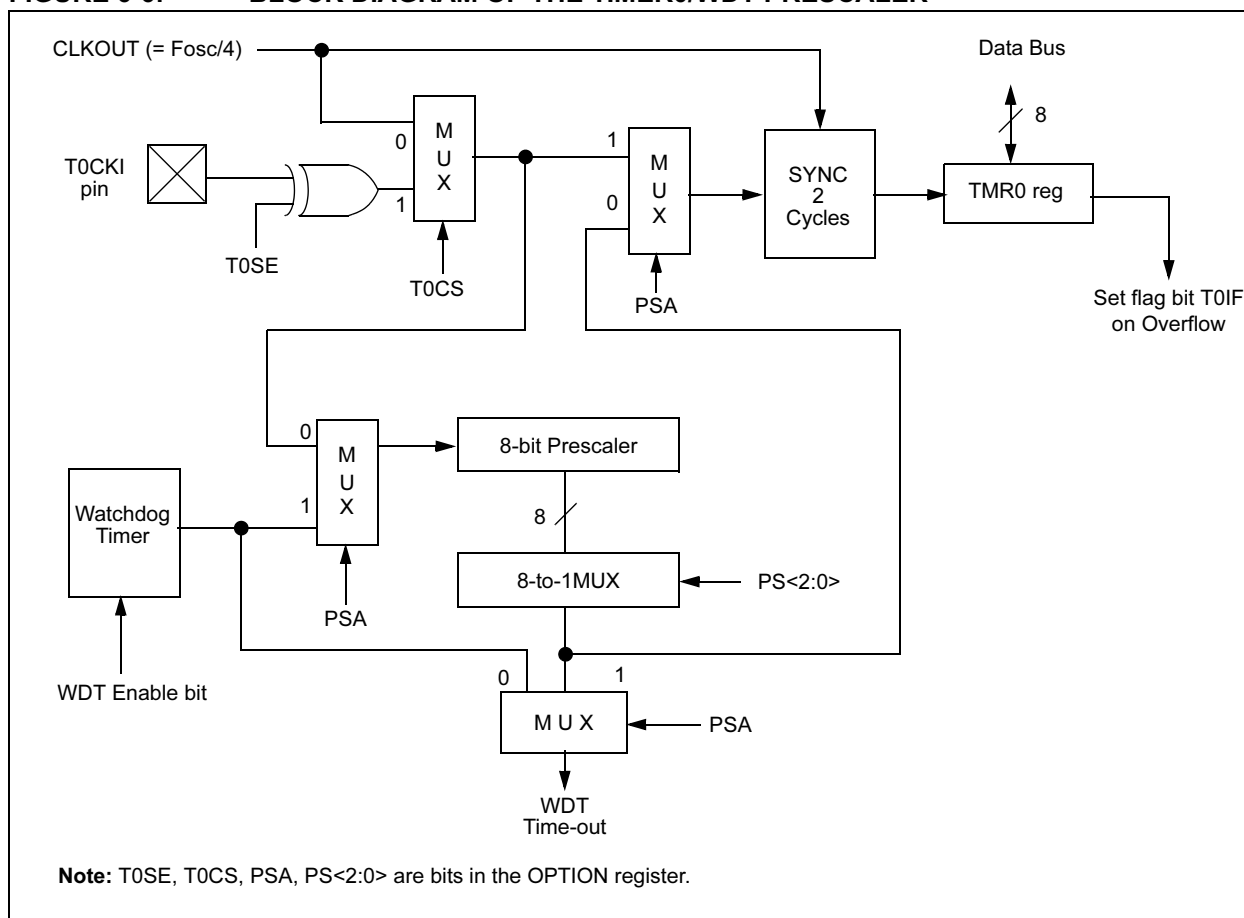
6.3 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscale for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusive between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1`, `MOVWF 1`, `BSF 1,x...etc.`) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

FIGURE 6-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



PIC16C62X

9.9 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

9.10 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. Only the Least Significant 4 bits of the ID locations are used.

9.11 In-Circuit Serial Programming™

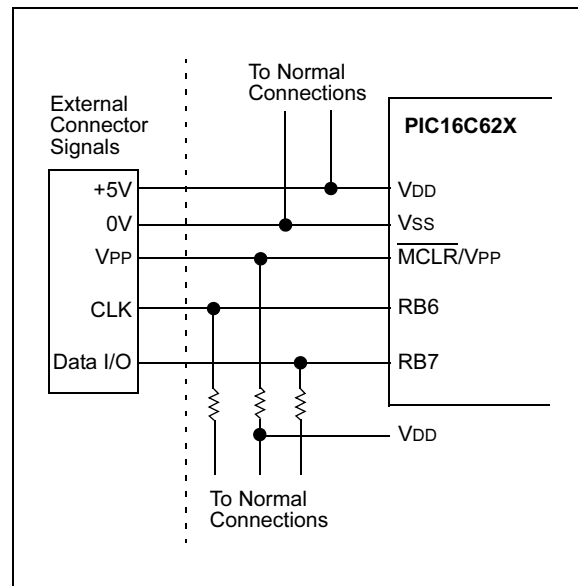
The PIC16C62X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RB6 and RB7 pins low, while raising the MCLR (VPP) pin from VIL to VIH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After RESET, to place the device into Programming/Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X/9XX Programming Specification (DS30228).

A typical In-Circuit Serial Programming connection is shown in Figure 9-19.

FIGURE 9-19: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



10.1 Instruction Descriptions

ADDLW Add Literal and W

Syntax:	[<i>label</i>] ADDLW <i>k</i>				
Operands:	$0 \leq k \leq 255$				
Operation:	$(W) + k \rightarrow (W)$				
Status Affected:	C, DC, Z				
Encoding:	<table border="1"><tr><td>11</td><td>111x</td><td>kkkk</td><td>kkkk</td></tr></table>	11	111x	kkkk	kkkk
11	111x	kkkk	kkkk		
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.				
Words:	1				
Cycles:	1				
Example	<pre>ADDLW 0x15</pre> Before Instruction W = 0x10 After Instruction W = 0x25				

ADDWF Add W and f

Syntax:	[<i>label</i>] ADDWF f,d			
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$			
Operation:	$(W) + (f) \rightarrow (\text{dest})$			
Status Affected:	C, DC, Z			
Encoding:	00	0111	dfff	ffff
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.			
Words:	1			
Cycles:	1			
Example	ADDWF FSR, 0			
	Before Instruction			
	W = 0x17			
	FSR = 0xC2			
	After Instruction			
	W = 0xD9			
	FSR = 0xC2			

ANDLW AND Literal with W

Syntax:	[<i>label</i>] ANDLW <i>k</i>				
Operands:	$0 \leq k \leq 255$				
Operation:	(W) .AND. (k) $\rightarrow$ (W)				
Status Affected:	Z				
Encoding:	<table border="1"><tr><td>11</td><td>1001</td><td>kkkk</td><td>kkkk</td></tr></table>	11	1001	kkkk	kkkk
11	1001	kkkk	kkkk		
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.				
Words:	1				
Cycles:	1				
Example	<pre>ANDLW 0x5F</pre> Before Instruction W = 0xA3 After Instruction W = 0x03				

ANDWF AND W with f

Syntax:	[<i>label</i>] ANDWF <i>f</i> , <i>d</i>				
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$				
Operation:	(W) .AND. (f) $\rightarrow$ (dest)				
Status Affected:	Z				
Encoding:	<table border="1"><tr><td>00</td><td>0101</td><td>dfff</td><td>ffff</td></tr></table>	00	0101	dfff	ffff
00	0101	dfff	ffff		
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example	<pre>ANDWF FSR, 1</pre> Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0x17 FSR = 0x02				

Bit Test f, Skip if Set																
Syntax:	[<i>label</i>] BTFSS f,b															
Operands:	$0 \leq f \leq 127$ $0 \leq b < 7$															
Operation:	skip if (f) = 1															
Status Affected:	None															
Encoding:	<table><tr><td>01</td><td>11bb</td><td>bfff</td><td>ffff</td></tr></table>	01	11bb	bfff	ffff											
01	11bb	bfff	ffff													
Description:	If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a two-cycle instruction.															
Words:	1															
Cycles:	1(2)															
Example	<table><tr><td>HERE</td><td>BTFSS</td><td>FLAG,1</td></tr><tr><td>FALSE</td><td>GOTO</td><td>PROCESS_CO</td></tr><tr><td>TRUE</td><td>•</td><td>DE</td></tr><tr><td></td><td>•</td><td></td></tr><tr><td></td><td>•</td><td></td></tr></table> Before Instruction PC = address HERE After Instruction if FLAG<1> = 0, PC = address FALSE if FLAG<1> = 1, PC = address TRUE	HERE	BTFSS	FLAG,1	FALSE	GOTO	PROCESS_CO	TRUE	•	DE		•			•	
HERE	BTFSS	FLAG,1														
FALSE	GOTO	PROCESS_CO														
TRUE	•	DE														
	•															
	•															

CALL		Call Subroutine							
Syntax:	[<i>label</i>] CALL k								
Operands:	$0 \leq k \leq 2047$								
Operation:	(PC)+ 1 → TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>								
Status Affected:	None								
Encoding:	<table border="1"><tr><td>10</td><td>0kkk</td><td>kkkk</td><td>kkkk</td></tr></table>					10	0kkk	kkkk	kkkk
10	0kkk	kkkk	kkkk						
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.								
Words:	1								
Cycles:	2								
Example	<pre>HERE CALL THER E</pre> Before Instruction PC = Address HERE After Instruction PC = Address THERE TOS = Address HERE+1								

CLRF		Clear f						
Syntax:	[<i>label</i>] CLRF f							
Operands:	$0 \leq f \leq 127$							
Operation:	00h → (f) 1 → Z							
Status Affected:	Z							
Encoding:	<table border="1"><tr><td>00</td><td>0001</td><td>1fff</td><td>ffff</td></tr></table>				00	0001	1fff	ffff
00	0001	1fff	ffff					
Description:	The contents of register 'f' are cleared and the Z bit is set.							
Words:	1							
Cycles:	1							
Example	<pre>CLRF FLAG_REG</pre> Before Instruction FLAG_REG = 0x5A After Instruction FLAG_REG = 0x00 Z = 1							

DECFSZ Decrement f, Skip if 0

Syntax: `[label] DECFSZ f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow (\text{dest}); \quad \text{skip if result} = 0$

Status Affected: None

Encoding:

00	1011	dfff	ffff
----	------	------	------

Description: The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
 If the result is 0, the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE      DECFSZ  CNT, 1
              GOTO   LOOP
CONTINUE  •
              •
              •
```

Before Instruction
 PC = address HERE

After Instruction
 CNT = CNT - 1
 if CNT = 0,
 PC = address CONTINUE
 if CNT $\neq$ 0,
 PC = address HERE+1

GOTO Unconditional Branch

Syntax: `[label] GOTO k`

Operands: $0 \leq k \leq 2047$

Operation: $k \rightarrow \text{PC}<10:0>$
 $\text{PCLATH}<4:3> \rightarrow \text{PC}<12:11>$

Status Affected: None

Encoding:

10	1kkk	kkkk	kkkk
----	------	------	------

Description: GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
GOTO THERE
```

After Instruction
 PC = Address THERE

INCF Increment f

Syntax: `[label] INCF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) + 1 \rightarrow (\text{dest})$

Status Affected: Z

Encoding:

00	1010	dfff	ffff
----	------	------	------

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```
INCF  CNT, 1
```

Before Instruction
 CNT = 0xFF
 Z = 0

After Instruction
 CNT = 0x00
 Z = 1

PIC16C62X

NOTES:

PIC16C62X

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D010	IDD	Supply Current ^(2, 4)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)*
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	—	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT mode, (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode
D020	IPD	Power-down Current ⁽³⁾	—	—	2.2	μA	VDD = 3.0V
			—	—	5.0	μA	VDD = 4.5V*
			—	—	9.0	μA	VDD = 5.5V
			—	—	15	μA	VDD = 5.5V Extended Temp.
D020	IPD	Power-down Current ⁽³⁾	—	—	2.0	μA	VDD = 2.5V
			—	—	2.2	μA	VDD = 3.0V*
			—	—	9.0	μA	VDD = 5.5V
			—	—	15	μA	VDD = 5.5V Extended Temp.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

PIC16C62X

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D030 D031 D032 D033	V _{IL}	Input Low Voltage					
		I/O ports					
		with TTL buffer	V _{SS}	—	0.8V 0.15 V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	V _{SS}	—	0.2 V _{DD}	V	(Note 1)
		$\overline{\text{MCLR}}$, RA4/T0CKI, OSC1 (in RC mode)	V _{SS}	—	0.2 V _{DD}	V	
D030 D031 D032 D033	V _{IL}	OSC1 (in XT and HS)	V _{SS}	—	0.3 V _{DD}	V	
		OSC1 (in LP)	V _{SS}	—	0.6 V _{DD} - 1.0	V	
D030 D031 D032 D033	V _{IL}	Input Low Voltage					
		I/O ports					
		with TTL buffer	V _{SS}	—	0.8V 0.15 V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	V _{SS}	—	0.2 V _{DD}	V	(Note 1)
		$\overline{\text{MCLR}}$, RA4/T0CKI, OSC1 (in RC mode)	V _{SS}	—	0.2 V _{DD}	V	
D030 D031 D032 D033	V _{IL}	OSC1 (in XT and HS)	V _{SS}	—	0.3 V _{DD}	V	
		OSC1 (in LP)	V _{SS}	—	0.6 V _{DD} - 1.0	V	
D040 D041 D042 D043 D043A	V _{IH}	Input High Voltage					
		I/O ports					
		with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}	V	(Note 1)
		$\overline{\text{MCLR}}$ RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A	V _{IH}	OSC1 (XT, HS and LP)	0.7 V _{DD}	—	V _{DD}	V	
		OSC1 (in RC mode)	0.9 V _{DD}	—	V _{DD}	V	(Note 1)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.
- 2:** The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3:** Negative current is defined as coming out of the pin.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D040	V _{IH}	Input High Voltage I/O ports with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise (Note 1)
D041		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}	V	
D042		MCLR RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V _{DD} 0.9 V _{DD}	—	V _{DD}	V	
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D060	I _{IL}	Input Leakage Current ^(2, 3) I/O ports (Except PORTA)	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D061		PORTA	—	—	±0.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance
D063		RA4/T0CKI	—	—	±1.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
D063		OSC1, MCLR	—	—	±5.0	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP osc configuration
D080	V _{OL}	Output Low Voltage I/O ports	—	—	0.6	V	I _{OL} = 8.5 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 7.0 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 1.6 mA, V _{DD} = 4.5V, -40° to $+85^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I _{OL} = 1.2 mA, V _{DD} = 4.5V, $+125^{\circ}\text{C}$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.6 DC Characteristics: PIC16C620A/C621A/C622A-40⁽³⁾ (Commercial) PIC16CR620A-40⁽³⁾ (Commercial)

DC CHARACTERISTICS Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	Sym	Min	Typ ⁽¹⁾	Max	Units	Conditions
Supply Voltage	VDD	4.5	—	5.5	V	HS Option from 20 - 40 MHz
Supply Current ⁽²⁾	IDD	—	5.5 7.7	11.5 16	mA mA	FOSC = 40 MHz, VDD = 4.5V, HS mode FOSC = 40 MHz, VDD = 5.5V, HS mode
HS Oscillator Operating Frequency	FOSC	20	—	40	MHz	OSC1 pin is externally driven, OSC2 pin not connected
Input Low Voltage OSC1	VIL	VSS	—	0.2VDD	V	HS mode, OSC1 externally driven
Input High Voltage OSC1	VIH	0.8VDD	—	VDD	V	HS mode, OSC1 externally driven

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS,
T0CKI = VDD, MCLR = VDD; WDT disabled, HS mode with OSC2 not connected.

3: For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

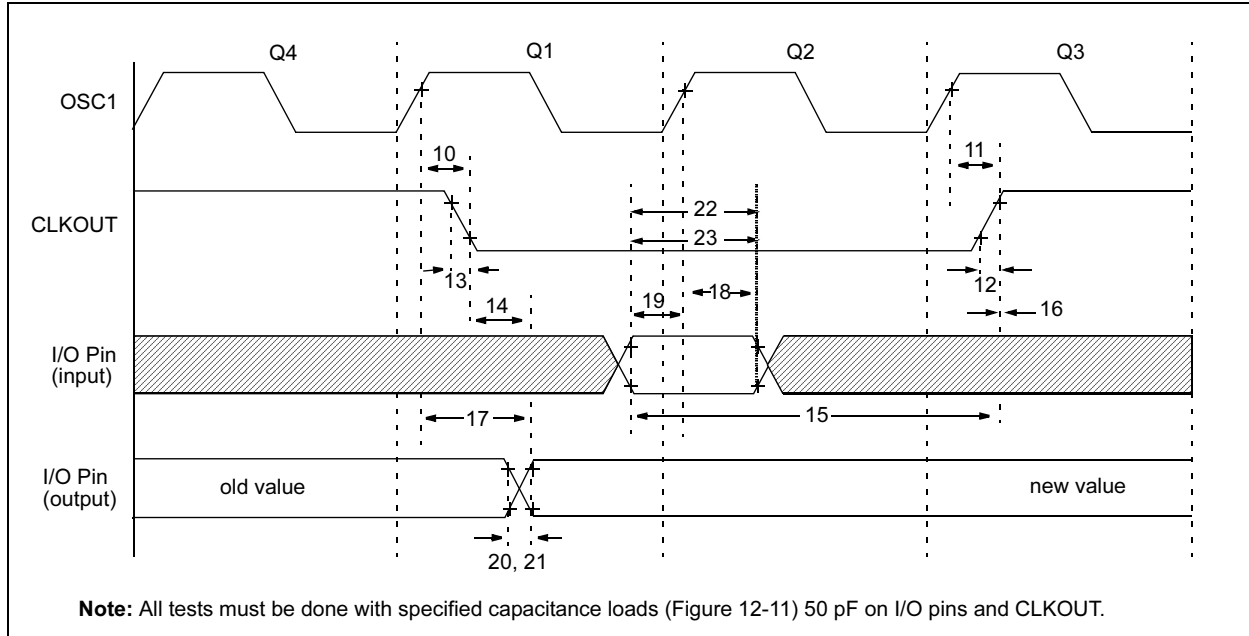
12.7 AC Characteristics: PIC16C620A/C621A/C622A-40⁽²⁾ (Commercial) PIC16CR620A-40⁽²⁾ (Commercial)

AC CHARACTERISTICS All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	Sym	Min	Typ ⁽¹⁾	Max	Units	Conditions
External CLKIN Frequency	FOSC	20	—	40	MHz	HS mode, OSC1 externally driven
External CLKIN Period	Tosc	25	—	50	ns	HS mode (40), OSC1 externally driven
Clock in (OSC1) Low or High Time	TosL, TosH	6	—	—	ns	HS mode, OSC1 externally driven
Clock in (OSC1) Rise or Fall Time	TosR, TosF	—	—	6.5	ns	HS mode, OSC1 externally driven
OSC1↑ (Q1 cycle) to Port out valid	TosH2ioV	—	—	100	ns	—
OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TosH2ioI	50	—	—	ns	—

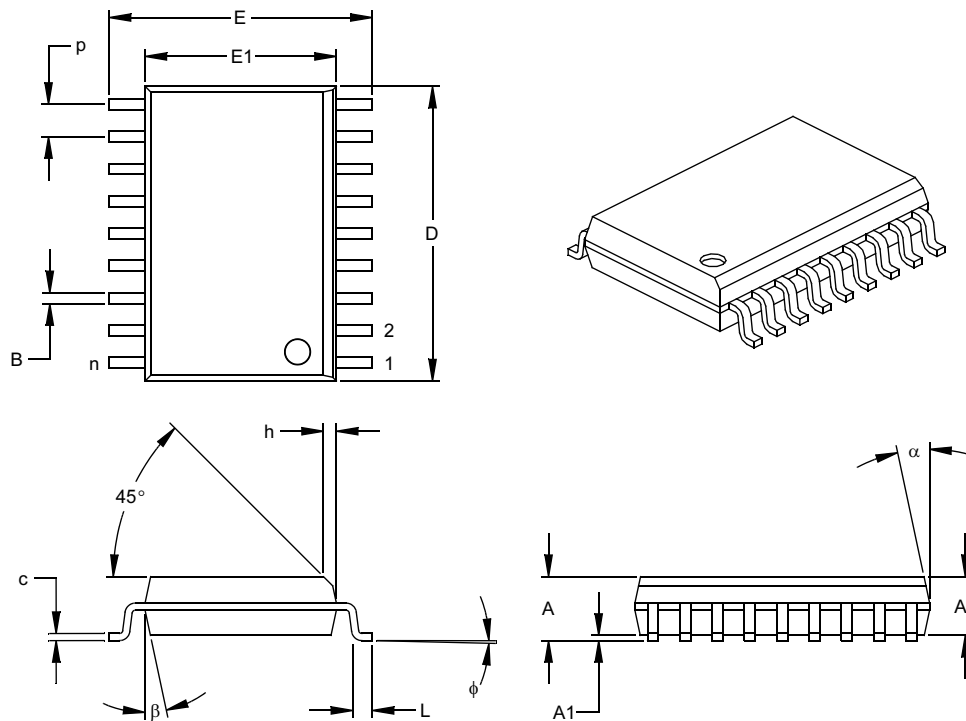
Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

FIGURE 12-13: CLKOUT AND I/O TIMING



18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

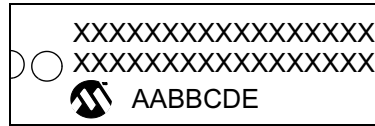
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

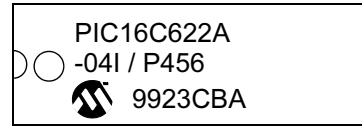
Drawing No. C04-051

14.1 Package Marking Information

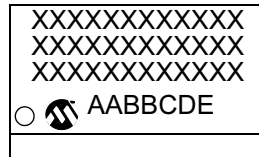
18-Lead PDIP



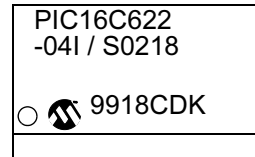
Example



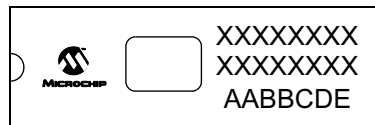
18-Lead SOIC (.300")



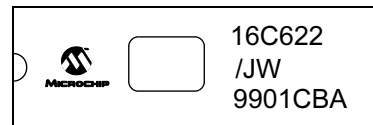
Example



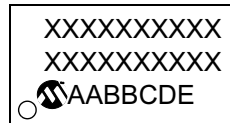
18-Lead Cerdip Windowed



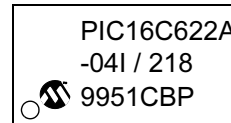
Example



20-Lead SSOP



Example



Legend: XX...X Customer specific information*
 Y Year code (last digit of calendar year)
 YY Year code (last 2 digits of calendar year)
 WW Week code (week of January 1 is week '01')
 NNN Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.